



PacTech
member of nagase group

MegaPac MP300A

**Megasonic Cleaning Unit
with QDR and Wafer Handling System**



Automatic MegaPac MP300A

The MegaPac MP300A is a system for automatic cleaning of flux residues from wafers after wafer level solder paste printing and solder paste reflow.

The wafer handling inside the system is done by robot handling. A horizontal panel is dividing the housing into an upper drip pan for the process-basin and a lower housing with a drip pan and leak Sensor. To reach the installations in the lower housing, there are sliding service doors made of PMMA brown on the front and insert doors on the rear, made of PMMA brown too.

The operating panel consists of a perforated plate with a free passage of approx. 25 % and gaps for the process modules. The upper drip pan gets vacuumed and can be adjusted modular. On the rear, there is housing with an insert door, made of PMMA brown, containing electrical and pneumatic components.

Technical Data and Facility Requirements: *MegaPac*

Mechanical Data

Dimensions L x W x H	approx. 1200 x 800 x 1800mm
Basin Size	approx. 370 x 370mm
Throughput	up to 50 wafer per hour (8") up to 25 wafer per hour (12")

Electrical Data & Ancillary Supply

Line Voltage	400V
Max. Current	25A
Frequency	50Hz
Power consumption	5kW
Heating Power	3kW
Circulation-Filtration	15l/min
Megasonic Frequency	1 MHz

MegaPac MP200



Manual MegaPac MP200

- Explosive Safe Construction
- Semi-Automatic PLC Control
- Additional QDR Rinse Tank
- Maximum Flexibility: 4-12"

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